

SOT807-1

plastic thermal enhanced ball grid array package; 156 balls;
body 15 x 15 x 1.15 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA156
Package type industry code	HBGA156
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	6-3-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.8	-	15	15.2	mm
E	package width		14.8	-	15	15.2	mm
A	seated height		[tbd]	-	1.75	1.75	mm
A ₂	package height		1.05	-	1.15	1.25	mm
n ₂	actual quantity of termination		-	-	156	-	



2. Package outline

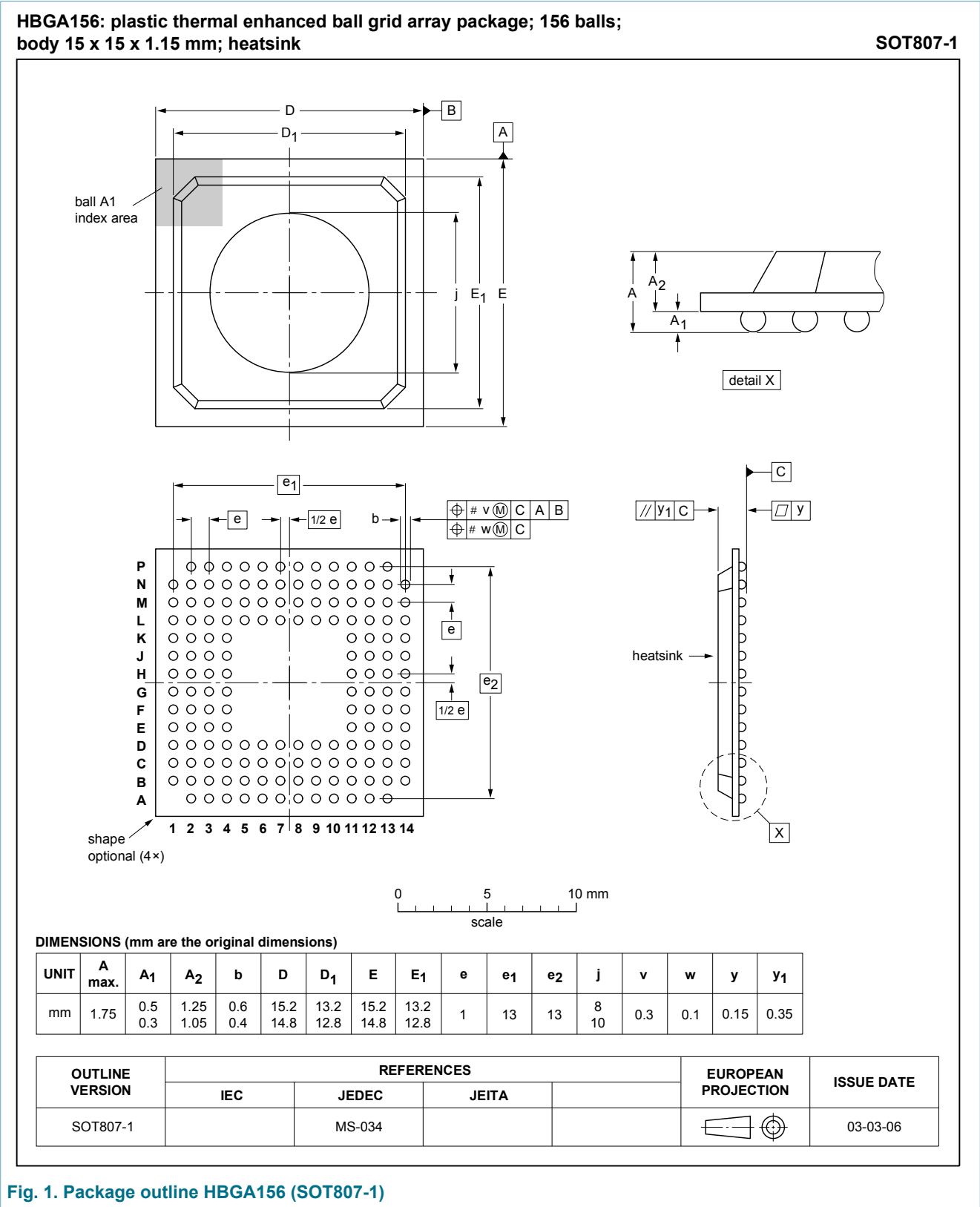


Fig. 1. Package outline HBGA156 (SOT807-1)

3. Soldering

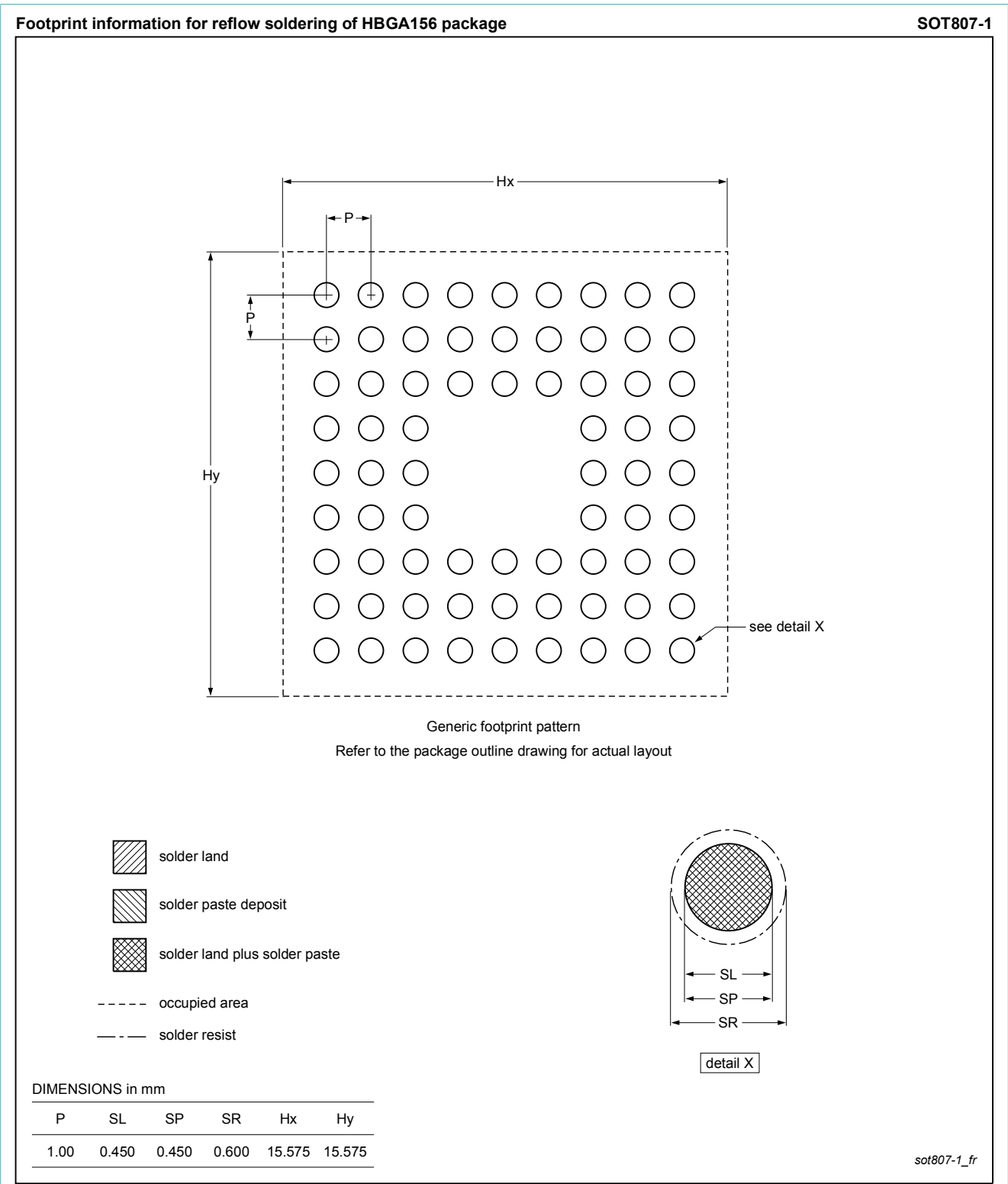


Fig. 2. Reflow soldering footprint for HBGA156 (SOT807-1)

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4. Legal information

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